

#### **EN:** This Datasheet is presented by the manufacturer.

Please visit our website for pricing and availability at <u>www.hestore.hu</u>.

### TinyLogic HS Inverter with Schmitt Trigger Input

### NC7S14

#### Description

The NC7S14 is a single high performance CMOS Inverter with Schmitt Trigger input. The circuit design provides hysteresis between the positive–going and negative going input thresholds thereby improving noise margins.

Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation over a broad  $V_{CC}$  range. ESD protection diodes inherently guard both input and output with respect to the  $V_{CC}$  and GND rails.

#### Features

- Space Saving SOT23-5, SC-74A and SC-88A 5-Lead Package
- Ultra Small MicroPak<sup>TM</sup> Leadless Package
- Schmitt Input Hysteresis: >1 V Typ
- High Speed:  $t_{PD} = 4.5$  ns Typ
- Low Quiescent Power:  $I_{CC} < 1 \mu A$
- Balanced Output Drive: 2 mA I<sub>OL</sub>, -2 mA I<sub>OH</sub>
- Broad V<sub>CC</sub> Operating Range: 2 V 6 V
- Balanced Propagation Delays
- Specified for 3 V Operation
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol



ININ	= 2-Digit Lot null Haceability Code
XY	= 2-Digit Date Code Format
Z	= Assembly Plant Code
Μ	= Date Code*

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

MARKING DIAGRAMS

#### **Pin Configurations**





#### **PIN DESCRIPTIONS**

Pin Name	Description
А	Input
Y	Output
NC	No Connect



#### Figure 3. MicroPak (Top Through View)

#### **FUNCTION TABLE** $(Y = \overline{A})$

Input	Output
А	Y
L	Н
Н	L

H = HIGH Logic Level

L = LOW Logic Level

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Paran	neter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	_	-20	mA
		V <sub>IN</sub> > V <sub>CC</sub>	-	+20	
V <sub>IN</sub>	DC Input Voltage		-0.5	V <sub>CC</sub> + 0.5	V
Ι <sub>ΟΚ</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	-	-20	mA
	V <sub>OUT</sub> > V <sub>CC</sub>		-	+20	
V <sub>OUT</sub>	V <sub>OUT</sub> DC Output Voltage		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>OUT</sub>	DC Output Source or Sink Current		-	±12.5	mA
$I_{CC} \text{ or } I_{GND}$	DC V <sub>CC</sub> or Ground Current per C	Dutput Pin	-	±25	mA
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
TJ	Junction Temperature		-	+150	°C
ΤL	T <sub>L</sub> Lead Temperature (Soldering, 10 Seconds)		-	+260	°C
PD	Power Dissipation in Still Air	SC-74A / SOT23-5	-	390	mW
		SC-88A	-	332	7
		MicroPak-6	_	812	1

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage		2.0	6.0	V
V <sub>IN</sub>	Input Voltage		0	V <sub>CC</sub>	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
$\theta_{JA}$	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	
		MicroPak-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 1. Unused inputs must be held HIGH or LOW. They may not float.

#### DC ELECTICAL CHARACTERISTICS

				-	T <sub>A</sub> = +25°C	;	T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
VP	Positive Threshold Voltage	2.0 3.0 4.5 6.0		- - - -	1.29 1.90 2.73 3.56	1.5 2.2 3.15 4.2	- - - -	1.6 2.2 3.15 4.2	V
V <sub>N</sub>	Negative Threshold Voltage	2.0 3.0 4.5 6.0		0.3 0.6 1.13 1.5	0.70 1.05 1.66 2.24	- - - -	0.3 0.6 1.13 1.5		V
V <sub>H</sub>	Hysteresis Voltage	2.0 3.0 4.5 6.0		0.3 0.4 0.6 0.8	0.59 0.85 1.08 1.31	1.0 1.3 1.4 1.7	0.3 0.4 0.6 0.8	1.0 1.3 1.4 1.7	V
V <sub>OH</sub>	HIGH Level Output Voltage	2.0 3.0 4.5 6.0	$I_{OH} = -20 \ \mu A$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	1.90 2.90 4.40 5.90	2.0 3.0 4.5 6.0	- - - -	1.90 2.90 4.40 5.90	- - - -	V
		3.0 4.5 6.0	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -1.3 \text{ mA}$ $I_{OH} = -2.0 \text{ mA}$ $I_{OH} = -2.6 \text{ mA}$	2.68 4.18 5.68	2.87 4.37 5.86	- - -	2.63 4.13 5.63	- - -	V
V <sub>OL</sub>	LOW Level Output Voltage	2.0 3.0 4.5 6.0	$I_{OL} = 20 \ \mu A$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	- - - -	0.0 0.0 0.0 0.0	0.10 0.10 0.10 0.10	- - - -	0.10 0.10 0.10 0.10	V
		3.0 4.5 6.0	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 1.3 \text{ mA}$ $I_{OL} = 2.0 \text{ mA}$ $I_{OL} = 2.6 \text{ mA}$	- - -	0.1 0.1 0.1	0.26 0.26 0.26	- - -	0.33 0.33 0.33	V
I <sub>IN</sub>	Input Leakage Current	6.0	$V_{IN} = V_{CC}$ , GND	-	-	±0.1	-	±1.0	μA
I <sub>CC</sub>	Quiescent Supply Current	6.0	$V_{IN} = V_{CC}, \text{ GND}$	-	-	1.0	-	10.0	μA



#### AC ELECTRICAL CHARACTERISTICS

				٦	Γ <sub>A</sub> = +25°C	;	T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PLH,</sub>	Propagation Delay (Figure 4, 6)	5.0	C <sub>L</sub> = 15 pF	-	4.5	21	-	-	ns
<sup>t</sup> PHL		2.0 3.0 4.5 6.0	C <sub>L</sub> = 50 pF		20 12 8.5 7.5	100 27 20 17	- - -	125 35 25 21	ns
t <sub>TLH,</sub>	Output Transition Time	5.0	C <sub>L</sub> = 15 pF	-	3	8	-	-	ns
t <sub>THL</sub>	(Figure 4, 6)	2.0 3.0 4.5 6.0	C <sub>L</sub> = 50 pF	- - -	25 16 11 9	125 35 25 21	- - -	145 45 30 24	ns
C <sub>IN</sub>	Input Capacitance	Open		-	2	10	-	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Figure 5)	5.0	(Note 2)	_	7	-	-	-	pF

2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle.  $C_{PD}$  is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = ( $C_{PD}$ ) (V<sub>CC</sub>) ( $f_{IN}$ ) + (I<sub>CC</sub>static).

#### AC Loading and Waveforms



 $C_L$  includes load and stray capacitance Input PRR = 1.0 MHz;  $t_W$  = 500 ns

#### Figure 4. AC Test Circuit



Input = AC Waveforms; PRR = Variable; Duty Cycle = 50%.

Figure 5. I<sub>CCD</sub> Test Circuit



Figure 6. AC Waveforms



#### **ORDERING INFORMATION**

Part Number	Top Mark	Package Description	Shipping <sup>†</sup>
NC7S14M5X	7S14	SC-74A	3000 / Tape & Reel
NC7S14P5X	S14	SC-88A	3000 / Tape & Reel
NC7S14L6X	UU	SIP6, MicroPak	5000 / Tape & Reel

#### **DISCONTINUED** (Note 3)

NC7S14M5X-L22090	7S14	SOT23-5	3000 / Tape & Reel
NC7S14P5X-L22057	S14	SC-88A	3000 / Tape & Reel
NC7S14L6X-L22175	UU	SIP6, MicroPak	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

3. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on <u>www.onsemi.com</u>.

MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.





SIP6 1.45X1.0 CASE 127EB ISSUE O

DATE 31 AUG 2016



special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

#### SC-74A-5 3.00x1.50x0.95, 0.95P CASE 318BQ **ISSUE C** DATE 26 FEB 2024 NOTES: 5X b ⊕ 0.20 M C A B DIMENSIONING AND TOLERANCING CONFORM TO ASME 1. Y14.5-2018. 2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES). В 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, Ē 4 E1 PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. MILLIMETERS ○ 0.15 C DIM NOM. MIN. MAX. 2X е 0.90 1.00 1.10 А A A1 0.01 0.18 0.10 0.95 REF Α2 TOP VIEW 0.25 0.37 0.50 b DETAIL A (A2) 0.10 0.18 0.26 С Α D 2.85 3.00 3.15 Ε 2.75 BSC E1 1.35 1.50 1.65 0.05 C SEATING е 0.95 BSC Α1 Ċ PLANE END VIEW SIDE VIEW L 0.20 0.40 0.60 L1 0.62 REF 0.25 BSC 12 GAUGE PLANE L2 5° 10° Θ 0° 1.90 0.95 Ð, (L1)"A" DETAIL SCALE 2:1 2.40 GENERIC **MARKING DIAGRAM\*** 1.00 0.70 XXX M= -O RECOMMENDED MOUNTING FOOTPRINT\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING XXX = Specific Device Code = Date Code Μ TECHNIQUES REFERENCE MANUAL, SOLDERRM/D. = Pb-Free Package (Note: Microdot may be in either location) \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •" may or may not be present. Some products may not follow the Generic Marking. Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON66279G Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** SC-74A-5 3.00x1.50x0.95, 0.95P PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights of others.

#### www.onsemi.com

0

DATE 11 APR 2023



#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE. NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.



e

F1



#### RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

DIM	MI	LLIMETE	RS		
MIU	MIN,	NDM.	MAX.		
А	0.80	0.95	1.10		
A1			0.10		
A3		0.20 REF			
b	0.10	0.20	0.30		
C	0.10		0.25		
D	1.80	2.00	2.20		
E	2.00	2.10	2.20		
E1	1.15	1.25	1.35		
e		0.65 BSC			
L	0.10	0.15	0.30		

### **GENERIC MARKING**





\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

DESCRIPTION:	SC-88A (SC-70-				PAGE 1 OF 1
DOCUMENT NUMBER:	98ASB42984B			ot when accessed directly from when stamped "CONTROLLED	
STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 1 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	Note: Please refer to style callout. If style t out in the datasheet i datasheet pinout or p	type is not called refer to the device
STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR 5. CATHODE	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2	STYLE 5: PIN 1. CATHODE 2. COMMON ANOE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4	DE

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights or the rights of others.



PIN 1

REFERENCE

#### SOT-23, 5 Lead CASE 527AH ISSUE A

DATE 09 JUN 2021

NDTES:

A

F1 F

В

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.



-e

TOP VIEW



GENERIC MARKING DIAGRAM\*



XXX = Specific Device CodeM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

	MILLIMETERS				
DIM	MIN.	NDM.	MAX.		
Α	0.90	—	1.45		
A1	0.00	_	0.15		
A2	0.90	1.15	1.30		
b	0.30	—	0.50		
С	0.08	—	0.22		
D	2.90 BSC				
E	2.80 BSC				
E1	1	.60 BSC			
e	0	.95 BSC			
L	0.30	0.45	0.60		
L1	0	.60 REF			
L2	0	.25 REF			
θ	0*	4°	8*		
01	0*	10°	15°		
θ2	0*	10*	15°		



#### RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

DOCUMENT NUMBER:	98AON34320E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOT-23, 5 LEAD		PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com

ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales